

5x7mm Precision TCXO Model DV75D

Description:

The Connor-Winfield's DV75D is a 5x7mm Surface Mount Temperature Compensated Crystal Controlled Oscillator (TCXO) with LVCMOS output. Through the use of Analog Temperature Compensation, the DV75D is capable of holding sub 1-ppm stabilities over the -40 to 85°C temperature range.

Applications:

GR-253-CORE (SMC) ITU-T-G.813 Option 1 and 2 (SEC)



- Features:
- TCXO
- 3.3 Vdc Operation
- LVCMOS Output
- Frequency Stability: ± 1.0 ppm
- Temperature Range: -40 to 85°C
- Low Jitter <1ps RMS
- 5x7mm Surface Mount Package
- Tape and Reel Packaging
- RoHS Compliant / Pb Free

Absolute Maximum Ratings

Parameter	Minimum	Nominal	Maximum	Units	Notes
Storage Temperature	-55	-	85	°C	
Supply Voltage (Vcc)	-0.5	-	6.0	Vdc	
Input Voltage	-0.5	-	Vcc+0.5	Vdc	

Operating Specifications					
Parameter	Minimum	Nominal	Maximum	Units	Notes
Nominal Frequency (Fo)	-	10.0, 12.8 or 20.0	-	MHz	
Frequency Calibration @ 25 °C	-1.0	-	1.0	ppm	1
Frequency Stability vs. Temperature	-1.0	-	1.0	ppm	2
Frequency vs. Load Stability	-0.2	-	0.2	ppm	±5%
Frequency vs. Voltage Stability	-0.2	-	0.2	ppm	±5%
Static Temperature Hysteresis	-	-	0.4	ppm	3
Aging	-1.0	-	1.0	ppm/year	
Operating Temperature Range:	-40	-	85	°C	
Supply Voltage (Vcc)	3.135	3.3	3.465	Vdc	±5%
Supply Current (Icc)	-	-	6	mA	
Period Jitter	-	3	5	ps rms	
Integrated Phase Jitter	-	0.5	1.0	ps rms	4
Typical Phase Noise Fo = 20.0 MHz					
SSB Phase Noise at 10Hz offset	-	-80	-	dBc/Hz	
SSB Phase Noise at 100Hz offset	-	-110	-	dBc/Hz	
SSB Phase Noise at 1KHz offset	-	-135	-	dBc/Hz	
SSB Phase Noise at 10KHz offset	-	-150	-	dBc/Hz	
SSB Phase Noise at 100KHz offset	-	-150	-	dBc/Hz	
Start-up Time	-	-	10	ms	

LVCMOS Output Characteristics

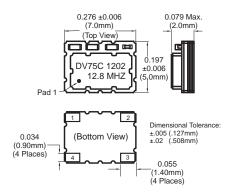
Parameter	Minimum	Nominal	Maximum	Units	Notes
Load	-	15	-	pF	5
Voltage (High) (Voh)	90%Vcc	-	-	Vdc	
(Low) (Vol)	-	-	10%Vcc	Vdc	
Duty Cycle at 50% of Vcc	45	50	55	%	
Rise / Fall Time 10% to 90%	-	-	8	ns	

Package Characteristics

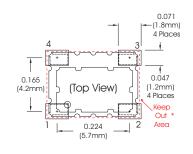
	J			
Package	Hermetically sealed crystal mounted on a ceramic package			
	Environmental Characteristics			
Vibration:	Vibration per Mil Std 883E Method 2007.3 Test Condition A			
Shock:	Mechanical Shock per Mil Std 883E Method 2002.4 Test Condition B.			
Soldering Process;	RoHS compliant lead free. See soldering profile on page 2.			



Package Layout



Suggested Pad Layout

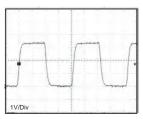


* Do not route any traces in the keep out area. It is recommended the next layer under the keep out area is to be ground plane.

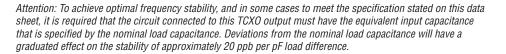
Pad Connections

1:	N/C
2:	Ground
3:	Output (Fo)
4:	Supply Voltage (Vcc)

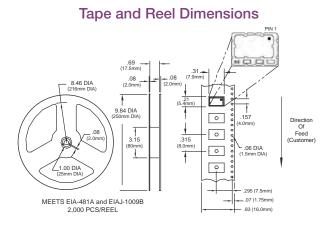
Output Waveform



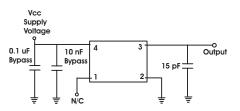
0.010"(0.254mm) 50 Ohm trace ecommendi clearance inductance for internal Vcc <1"by design opper flood Buffer Ground Top View Ground Top View 50 Ohm Trace Without Output Vias Buffer TOP LAY GROUND LAYER



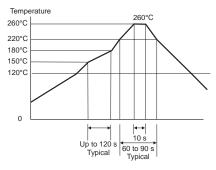
BOTTOM LAYER



Test Circuit



Solder Profile



Meets IPC/JEDEC J-STD-020C

Design Recommendations

CEOB2B晶振平台-全球最专业的晶振在线采购查询平台http://www.crystal95.com